



1/28/13

Docket No.: M4065.0226/P226  
(PATENT)

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Patent Application of:  
Tongbi Jiang

Application No.: 09/484,437

Confirmation No.: 9698

Filed: January 18, 2000

Art Unit: 2813

For: Die attach curing method for semiconductor  
device

Examiner: J. M. Mitchell

**SUPPLEMENTAL AMENDMENT**

**MS Amendment**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

**INTRODUCTORY COMMENTS**

In response to the communication from the Office mailed April 23, 2008, please amend the above-identified U.S. patent application as follows:

**Amendments to the Claims** are reflected in the listing of claims which begins on page 2 of this paper and replaces the listing of claims filed with the Amendment of January 30, 2008.

**Remarks** begin on page 6 of this paper.